# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

[List multiple models if applicable.]

- HP 430 Notebook PC
- Name / Model #3
- Name / Model #4
- Name / Model #5

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers
Components, parts and materials containing radioactive substances

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Automatic crossing screw driver</td>
<td>Philip #1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the Battery, and loosen screws on logic lower.
2. Get HDD, ODD and memory.
3. Remove KB, Pull out connecter.
4. Remove C cover
5. Pull out the DC IN cable, HDD connecter, ODD connecter, and USB Board cable, Remove Speaker cable from MB.
6. Loosen screw on WLAN and remove antenna.
7. Remove the MB, take down the thermal module and the CPU.
8. Remove LCD module, tear down LCD Cover.
9. Remove panel and camera

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
**Work Instructs**

**Document No.**: Disassembly WI  **Step**: 1

**Name**: Get Battery  **Date**: 2011-1-13

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**Step**: 

1. Push the Battery switch and take off the battery. (Fig.1)
2. Loosen eight screws on Battery house and take off Memory Door. (Fig.2)

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<table>
<thead>
<tr>
<th>Fixture list(Fixture standard)</th>
<th>Qty</th>
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<th>Qty</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cross Head of Screws Driver</td>
<td>1</td>
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</table>

*Point for attention: If finding some defects, notice the gaffer and assess.*
Work Instructs

Document No.: Disassembly WI

Step: 2

Name: Get HDD/Memory/ODD

Date: 2011-1-13

Step:

1. Loosen four screws and pull out the WLAN cable and power cable. (Fig.1)

2. Take off Memory, WLAN, HDD door and ODD. (Fig.1)

3. Loosen four screws and pull out HDD cable from MB. (Fig.2)

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</table>
Step:

1. Loosen four screws on HDD door. (Fig.1)
2. Loosen ten screws. (Fig.2)
3. Take off the keyboard from top side, set at an angle of 45 degrees. (Fig.3)

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Work Instructs

Document No. : Disassembly WI                               Step : 4
Name : Remove C cover                                      Date : 2011-1-13

Step:

1. Pull out the POWER BUTTON BOARD Cable.(Fig.1)
2. Remove the TB Cable.(Fig.2)
3. Loosen the screws and breakaway the logic upper along the arrowhead. (Fig.3)

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Work Instructs

Document No. : Disassembly WI  
Step : 5

Name : Disassemble C cover  
Date : 2011-1-13

Step:

1. Pull out the TP cable. (Fig.1)

2. Loosen two screws the and take off the POWER BUTTON BOARD. (Fig.2)

3. Loosen seven screws and remove the TP bracket. (Fig.3)

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Work Instructs

Document No.: Disassembly WI  Step: 6
Name: Get Mother Board  Date: 2011-1-13

Step:

1. Take off RTC battery. (Fig.1)
2. Pull out LVDS/FAN cable/ Speaker cable/HDD cable/USB Board cable from MB. (Fig.1)
3. Loosen the screw and remove USB Board. (Fig.2)
4. Loosen four screws and take off Speaker. (Fig.3)
5. Loosen the screw and take off the MB. (Fig.1)

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Work Instructs

Document No. : Disassembly WI  
Name: Remove Thermal Module and CPU  
Step : 7  
Date : 2011-1-13

Step:

1. Loosen six screws and remove the Thermal Module. (Fig.1)

2. Turn the CPU lock 90 degree and get the CPU. (Fig.2)

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Work Instructs

Document No. : Disassembly WI   Step : 8

Name : Remove D cover   Date : 2011-1-13

Step:

1. Loosen four screws and take off the panel from D cover. (Fig.1)

2. Loosen two screws and remove HDD cable. (Fig.2)

3. Loosen two screws and take off Power cable. (Fig.3)

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Work Instructs

Document No. : Disassembly WI  Step : 9
Name : Get LCD panel  Date : 2011-1-13

Step:

1. Uncover two horned Mylar then loosen two screws.(Fig.1)
2. Breakaway the LCD bezel along the arrowhead.(Fig.2)
3. Loosen two screws and remove the Hinge Caps. (Fig.3)

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Work Instructs

Document No.: Disassembly WI

Step: 9
Name: Get LCD panel
Date: 2011-1-13

Step:
4. Loosen six screws. (Fig.1)
5. Turn over LCD and pull out the LVDS connector. (Fig.2)
6. Loosen six screws and remove the Hinges. (Fig.3)

Fixtures list (Fixture standard)

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Work Instructs

Document No. : Disassembly WI
Name : Remove camera

Step:

1. Pull out the LVDS form camera and tear up the LVDS cable along the arrowhead. (Fig.1)

2. Tear up the camera from A cover along the arrowhead. (Fig.2)

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